


S2ABF THRU S2MBF

SURFACE MOUNT GENERAL PURPOSE RECTIFIERS



VOLTAGE: 50~1000 Volts	CURRENT: 2.0 Amperes	SMBF	Marking and Polarity
FEATURES <ul style="list-style-type: none"> Glass passivated chip junction Low Forward Voltage Drop for high efficiency Low leakage current for high reliability High forward surge capability for high reliability 		 <p>Remark:</p> <ol style="list-style-type: none"> NH=niuhang trademark FF=Product line,According to actual changes; YWW=Periodic code,According to actual changes; S2xBF=Modle,x=A,B,D,G,J,K,M White band denotes cathode 	
MECHANICAL DATA <ul style="list-style-type: none"> Terminals: Plated Leads Solderable per MIL-STD-202, Method 208 Mounting Position: Any Lead Free: Lead Free Finish, RoHS Compliant Weight:App. 0.066 grams (0.0023 ounce) 			
TYPICAL APPLICATIONS <ul style="list-style-type: none"> For use in high frequency inverters ,AC/DC converters, DC/DC converters,LED driver etc. applications 			

Maximum Ratings (Ratings at 25°C ambient temperature unless otherwise specified.)

Parameter	Symbol	S2ABF	S2BBF	S2DBF	S2GBF	S2JBF	S2KBF	S2MBF	Unit
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current(see fig.1)	$I_{F(AV)}$	2.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC method at rated TL)(see fig.5)	I_{FSM}	60							A
Current Squared Time Per Diode(t<8.3ms)	I^2t	14.94							A ² sec

Electrical Characteristics (Ratings at 25°C ambient temperature unless otherwise specified).

Parameter	Test Conditions		Symbol	S2ABF	S2BBF	S2DBF	S2GBF	S2JBF	S2KBF	S2MBF	Unit
	$T_A=25^\circ C$	$T_A=125^\circ C$									
Maximum instantaneous forward voltage (see fig.2) (Note 1)	$I_F= 2.0$ A		V_F	1.10					V		
	$I_F= 2.0$ A			1.05							
Maximum instantaneous reverse current at rated DC blocking voltage (see fig.3)(Note 1)	$V_R= V_{RRM}$		I_R	5					uA		
	$V_R= 80\%*V_{RRM}$			200							
Typical junction capacitance(see fig.4)	4V,1MHz		C_J	50					pF		

Thermal Characterstcs (Ratings at 25°C ambient temperature unless otherwise specified)

Parameter	Symbol	S2ABF	S2BBF	S2DBF	S2GBF	S2JBF	S2KBF	S2MBF	Unit
Operating junction	T_J	-55 to 150							°C
Storage temperature range	T_{STG}	-55 to 150							
Typical thermal resistance (Note 2)	$R_{\theta JA}$	55					°C/W		
	$R_{\theta JC}$	17							

Note: 1.Pulse width < 300 uS, Duty cycle < 2%

2.P. C. B mounted with 0.3"*0.3"(7.62 x 7.62 mm) copper Pad Areas

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RATING AND CHARACTERISTIC CURVES

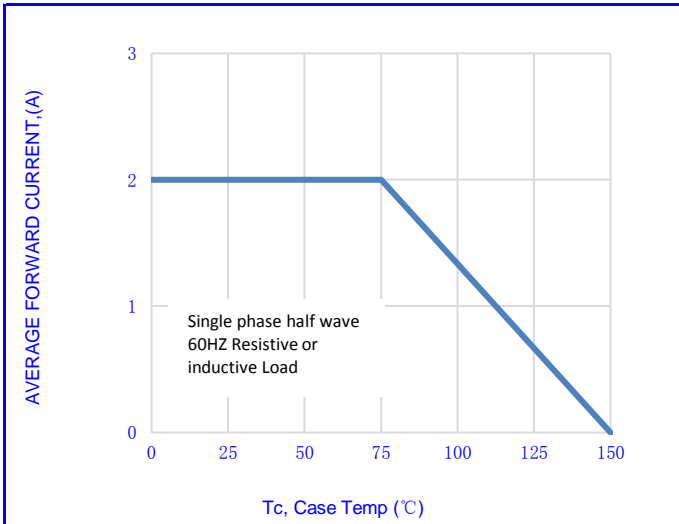


Fig.1- FORWARD CURRENT DERATING CURVE

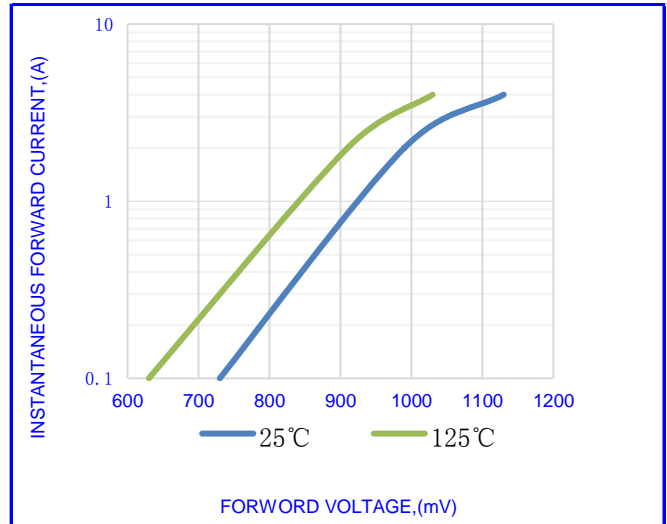


Fig.2-TYPICAL INSTANTANEOUS FORWARD

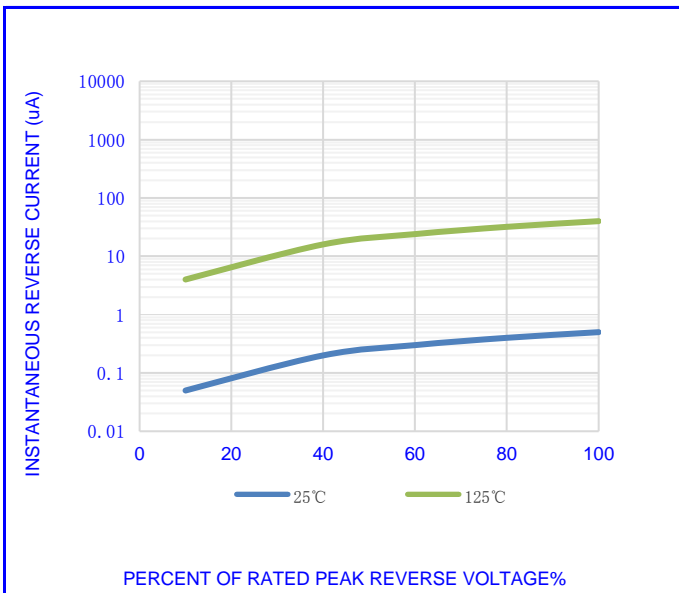


Fig.3-TYPICAL REVERSE CHARACTERISTICS

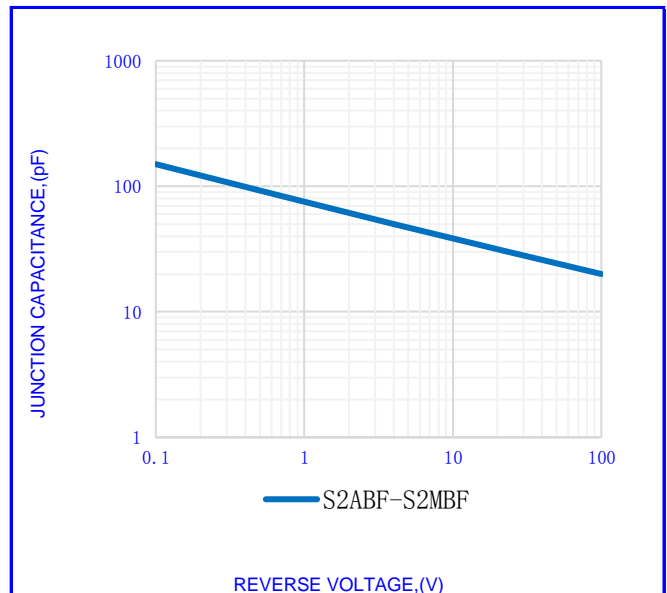


Fig.4- TYPICAL JUNCTION CAPACITANCE

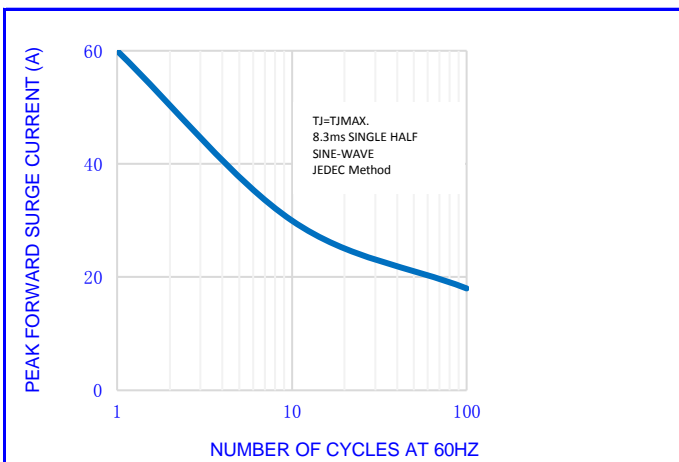


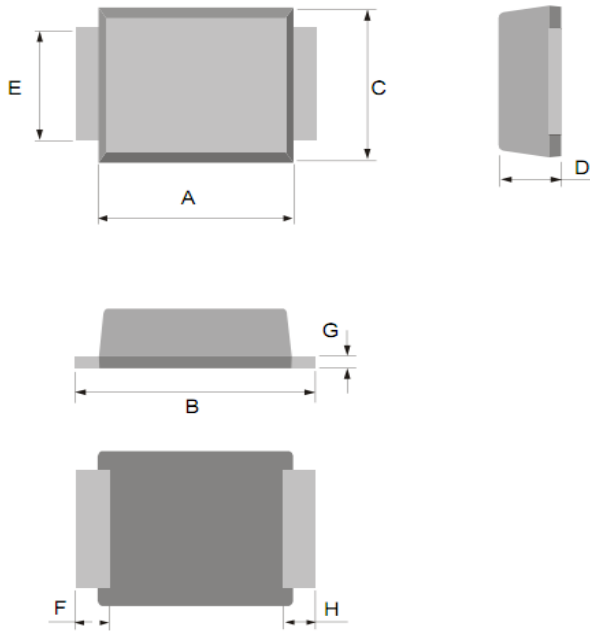
Fig.5-MAX. NON-REPETITIVE SURGE CURRENT

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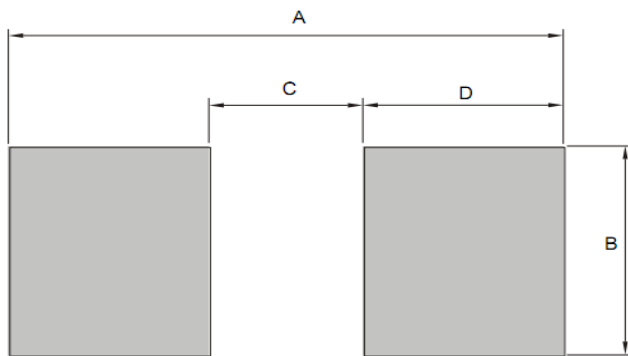
OUTLINE DRAWINGS



SMBF

OUTLINE DIMENSIONS						
Dim.	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.100	-	4.700	0.161	-	0.185
B	5.100	-	5.500	0.201	-	0.217
C	3.400	-	3.800	0.134	-	0.150
D	1.050	-	1.550	0.041	-	0.061
E	1.800	-	2.200	0.071	-	0.087
F	0.550	-	1.450	0.022	-	0.057
G	0.150	-	0.250	0.006	-	0.010
H	0.550	-	1.450	0.022	-	0.057

MOUNTING PAD LAYOUT



SMBF

OUTLINE DIMENSIONS						
Dim.	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	-	6.500	-	-	0.256	-
B	-	2.200	-	-	0.087	-
C	-	2.800	-	-	0.110	-
D	-	1.850	-	-	0.073	-

PACKING INFORMATION

SMBF

Package Method	Reel Size (mm)	Quantity (pcs/reel)	Inner Box Size LxWxH(mm)	Quantity (pcs/Inner Box)	Carton Size LxWxH(mm)	Quantity (pcs/carton)
Tape Reel	Φ330	5000	340x340x45	10000	360x360x470	100000

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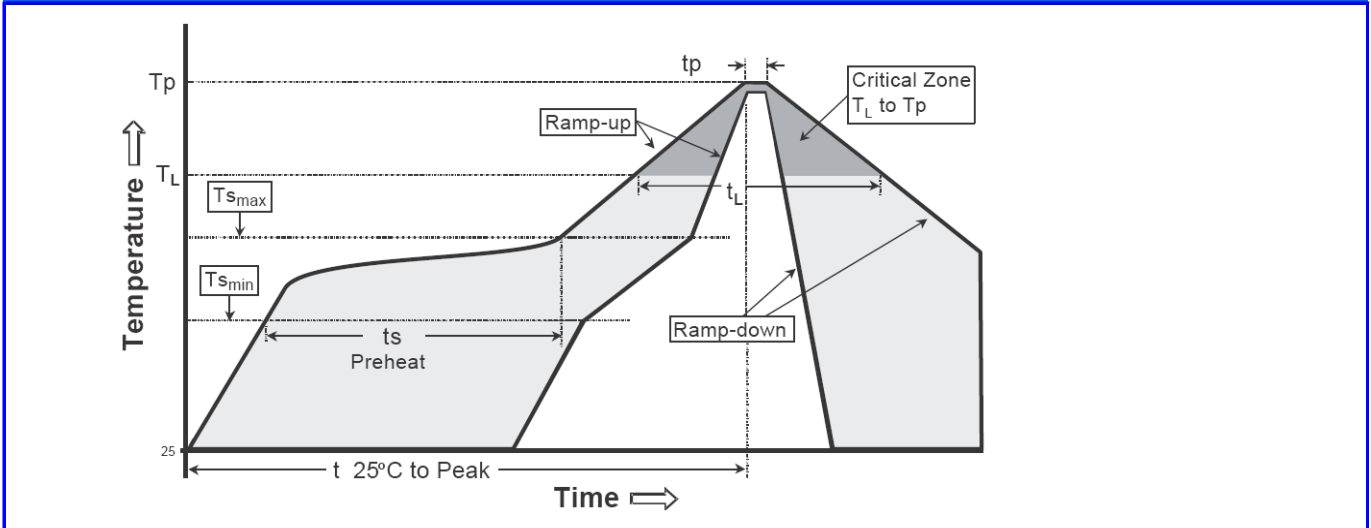
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Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmmax to Tp)	3°C/second max.	3°C/second max.
Preheat -Temperature Min(TS min) -Temperature Max(TS max) -Time(ts min to ts max)	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: -Temperature (TL) - Time (tL)	183°C 60-150 seconds	217°C 60-150 seconds
Peak Temperature(TP)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

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